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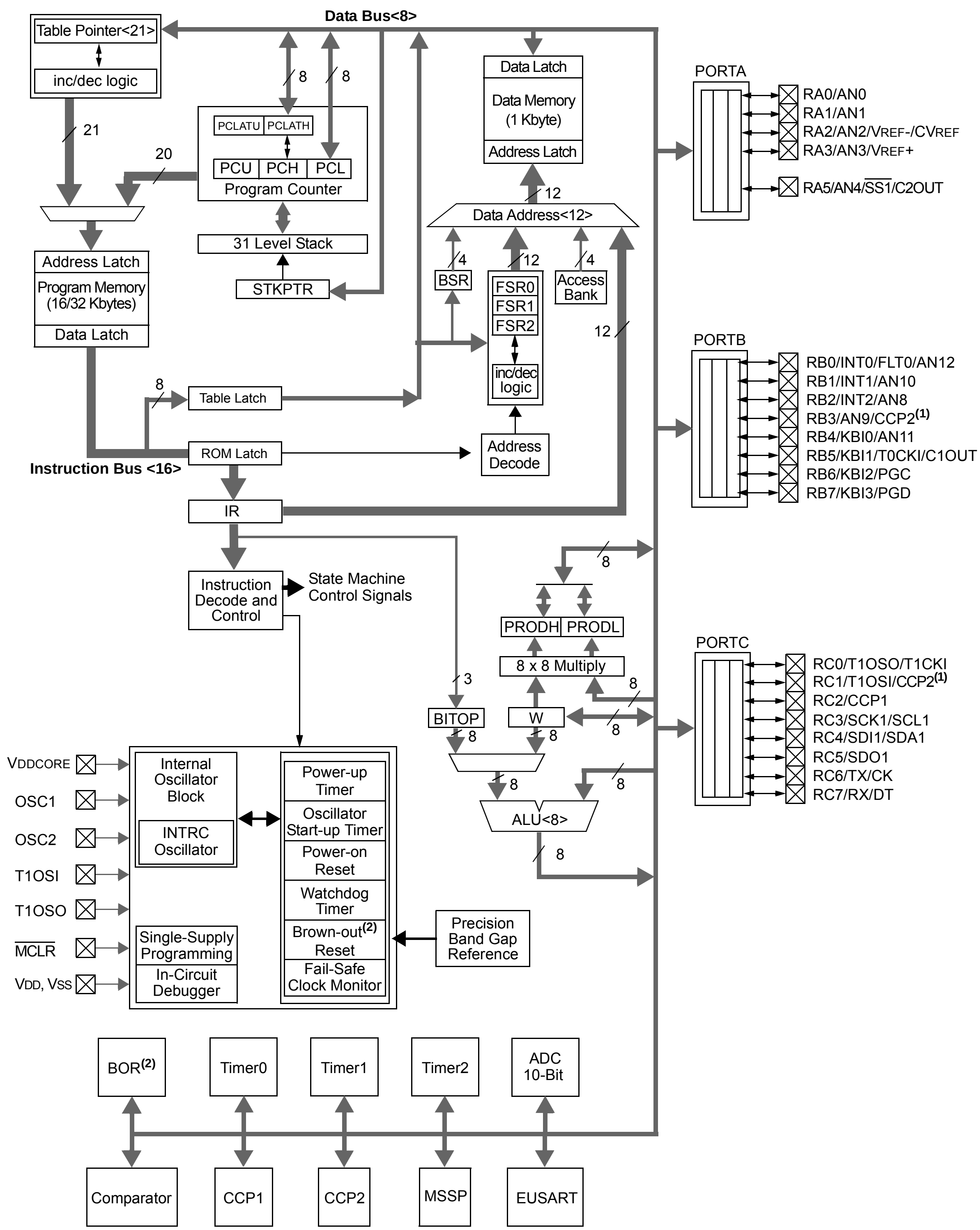
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f24j10-i-ss

FIGURE 1-1: PIC18F24J10/25J10 (28-PIN) BLOCK DIAGRAM



Note 1: CCP2 is multiplexed with RC1 when Configuration bit, CCP2MX, is set, or RB3 when CCP2MX is not set.

2: Brown-out Reset is not available in PIC18LF2XJ10/4XJ10 devices.

3.0 OSCILLATOR CONFIGURATIONS

3.1 Oscillator Types

The PIC18F45J10 family of devices can be operated in five different oscillator modes:

1. HS High-Speed Crystal/Resonator
2. HSPLL High-Speed Crystal/Resonator with Software PLL Control
3. EC External Clock with FOSC/4 Output
4. ECPLL External Clock with Software PLL Control
5. INTRC Internal 31 kHz Oscillator

Four of these are selected by the user by programming the FOSC<2:0> Configuration bits. The fifth mode (INTRC) may be invoked under software control; it can also be configured as the default mode on device Resets.

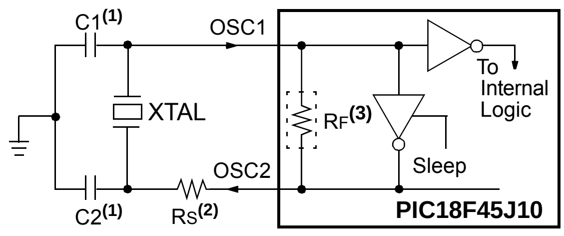
3.2 Crystal Oscillator/Ceramic Resonators (HS Modes)

In HS or HSPLL Oscillator modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation. Figure 3-1 shows the pin connections.

The oscillator design requires the use of a parallel cut crystal.

Note:	Use of a series cut crystal may give a frequency out of the crystal manufacturer's specifications.

FIGURE 3-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS OR HSPLL CONFIGURATION)



Note 1: See Table 3-1 and Table 3-2 for initial values of C1 and C2.

2: A series resistor (RS) may be required for AT strip cut crystals.

3: RF varies with the oscillator mode chosen.

TABLE 3-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Typical Capacitor Values Used:			
Mode	**Freq.**	**OSC1**	**OSC2**
HS	8.0 MHz 16.0 MHz	27 pF 22 pF	27 pF 22 pF

Capacitor values are for design guidance only.

These capacitors were tested with the resonators listed below for basic start-up and operation. **These values are not optimized**.

Different capacitor values may be required to produce acceptable oscillator operation. The user should test the performance of the oscillator over the expected VDD and temperature range for the application.

See the notes following Table 3-2 for additional information.

Resonators Used:
4.0 MHz
8.0 MHz
16.0 MHz

NOTES:

4.3 Sleep Mode

The power-managed Sleep mode is identical to the legacy Sleep mode offered in all other PIC microcontrollers. It is entered by clearing the IDLEN bit (the default state on device Reset) and executing the SLEEP instruction. This shuts down the selected oscillator (Figure 4-4). All clock source status bits are cleared.

Entering the Sleep mode from any other mode does not require a clock switch. This is because no clocks are needed once the controller has entered Sleep. If the WDT is selected, the INTRC source will continue to operate. If the Timer1 oscillator is enabled, it will also continue to run.

When a wake event occurs in Sleep mode (by interrupt, Reset or WDT time-out), the device will not be clocked until the clock source selected by the SCS<1:0> bits becomes ready (see Figure 4-5), or it will be clocked from the internal oscillator if either the Two-Speed Start-up or the Fail-Safe Clock Monitor are enabled (see **Section 21.0 “Special Features of the CPU”**). In either case, the OSTS bit is set when the primary clock is providing the device clocks. The IDLEN and SCS bits are not affected by the wake-up.

4.4 Idle Modes

The Idle modes allow the controller’s CPU to be selectively shut down while the peripherals continue to operate. Selecting a particular Idle mode allows users to further manage power consumption.

If the IDLEN bit is set to a ‘1’ when a SLEEP instruction is executed, the peripherals will be clocked from the clock source selected using the SCS<1:0> bits; however, the CPU will not be clocked. The clock source status bits are not affected. Setting IDLEN and executing a SLEEP instruction provides a quick method of switching from a given Run mode to its corresponding Idle mode.

If the WDT is selected, the INTRC source will continue to operate. If the Timer1 oscillator is enabled, it will also continue to run.

Since the CPU is not executing instructions, the only exits from any of the Idle modes are by interrupt, WDT time-out or a Reset. When a wake event occurs, CPU execution is delayed by an interval of T_{CSD} (parameter 38, Table 24-10) while it becomes ready to execute code. When the CPU begins executing code, it resumes with the same clock source for the current Idle mode. For example, when waking from RC_IDLE mode, the internal oscillator block will clock the CPU and peripherals (in other words, RC_RUN mode). The IDLEN and SCS bits are not affected by the wake-up.

While in any Idle mode or the Sleep mode, a WDT time-out will result in a WDT wake-up to the Run mode currently specified by the SCS<1:0> bits.

FIGURE 4-4: TRANSITION TIMING FOR ENTRY TO SLEEP MODE

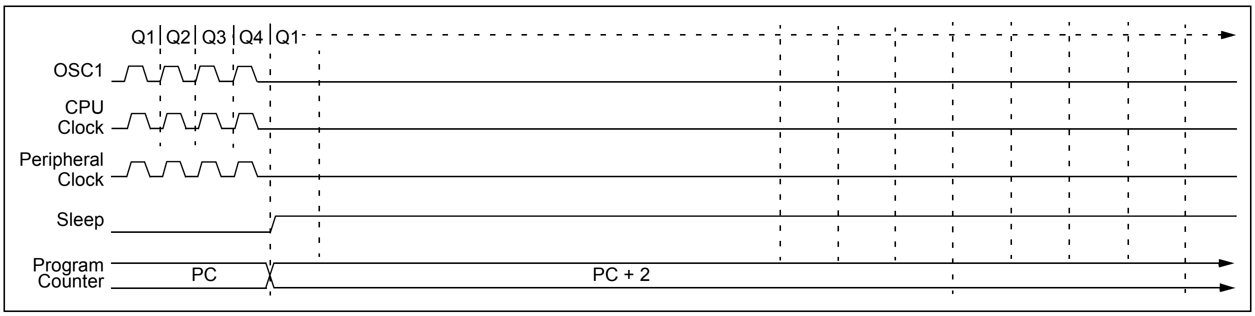
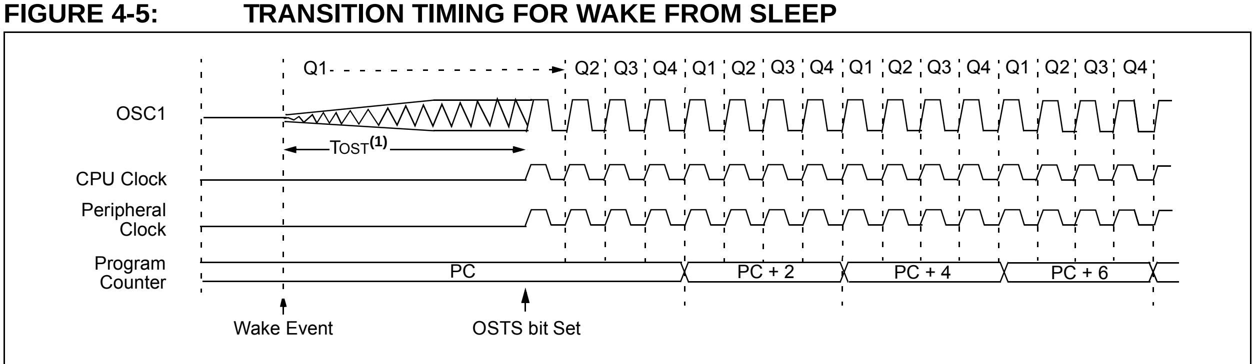


FIGURE 4-5: TRANSITION TIMING FOR WAKE FROM SLEEP



Note 1: T_{OST} = 1024 T_{OSC}. These intervals are not shown to scale.

TABLE 5-2: INITIALIZATION CONDITIONS FOR ALL REGISTERS (CONTINUED)

Register	Applicable Devices		Power-on Reset, Brown-out Reset	$\overline{MCLR}$ Resets, WDT Reset, RESET Instruction, Stack Resets, CM Resets	Wake-up via WDT or Interrupt
TRISE	PIC18F2XJ10	PIC18F4XJ10	0000 -111	1111 -111	uuuu -uuu
TRISD	PIC18F2XJ10	PIC18F4XJ10	1111 1111	1111 1111	uuuu uuuu
TRISC	PIC18F2XJ10	PIC18F4XJ10	1111 1111	1111 1111	uuuu uuuu
TRISB	PIC18F2XJ10	PIC18F4XJ10	1111 1111	1111 1111	uuuu uuuu
TRISA	PIC18F2XJ10	PIC18F4XJ10	--1- 1111	--1- 1111	--u- uuuu
SSP2BUF	PIC18F2XJ10	PIC18F4XJ10	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATE	PIC18F2XJ10	PIC18F4XJ10	---- -xxx	---- -uuu	---- -uuu
LATD	PIC18F2XJ10	PIC18F4XJ10	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATC	PIC18F2XJ10	PIC18F4XJ10	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATB	PIC18F2XJ10	PIC18F4XJ10	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATA	PIC18F2XJ10	PIC18F4XJ10	--xx xxxx	--uu uuuu	--uu uuuu
SSP2ADD	PIC18F2XJ10	PIC18F4XJ10	0000 0000	0000 0000	uuuu uuuu
SSP2STAT	PIC18F2XJ10	PIC18F4XJ10	0000 0000	0000 0000	uuuu uuuu
SSP2CON1	PIC18F2XJ10	PIC18F4XJ10	0000 0000	0000 0000	uuuu uuuu
SSP2CON2	PIC18F2XJ10	PIC18F4XJ10	0000 0000	0000 0000	uuuu uuuu
PORTE	PIC18F2XJ10	PIC18F4XJ10	---- -xxx	---- -uuu	---- -uuu
PORTD	PIC18F2XJ10	PIC18F4XJ10	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTC	PIC18F2XJ10	PIC18F4XJ10	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTB	PIC18F2XJ10	PIC18F4XJ10	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	PIC18F2XJ10	PIC18F4XJ10	--0- 0000	--0- 0000	--u- uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition. Shaded cells indicate conditions do not apply for the designated device.

Note 1: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the TOSU, TOSH and TOSL are updated with the current value of the PC. The STKPTR is modified to point to the next location in the hardware stack.

2: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the PC is loaded with the interrupt vector (0008h or 0018h).

3: One or more bits in the INTCONx or PIRx registers will be affected (to cause wake-up).

4: See Table 5-1 for Reset value for specific condition.

6.1.3 PROGRAM COUNTER

The Program Counter (PC) specifies the address of the instruction to fetch for execution. The PC is 21 bits wide and is contained in three separate 8-bit registers. The low byte, known as the PCL register, is both readable and writable. The high byte, or PCH register, contains the PC<15:8> bits; it is not directly readable or writable. Updates to the PCH register are performed through the PCLATH register. The upper byte is called PCU. This register contains the PC<20:16> bits; it is also not directly readable or writable. Updates to the PCU register are performed through the PCLATU register.

The contents of PCLATH and PCLATU are transferred to the program counter by any operation that writes PCL. Similarly, the upper two bytes of the program counter are transferred to PCLATH and PCLATU by an operation that reads PCL. This is useful for computed offsets to the PC (see **Section 6.1.6.1 "Computed GOTO"**).

The PC addresses bytes in the program memory. To prevent the PC from becoming misaligned with word instructions, the Least Significant bit of PCL is fixed to a value of '0'. The PC increments by 2 to address sequential instructions in the program memory.

The CALL, RCALL, GOTO and program branch instructions write to the program counter directly. For these instructions, the contents of PCLATH and PCLATU are not transferred to the program counter.

6.1.4 RETURN ADDRESS STACK

The return address stack allows any combination of up to 31 program calls and interrupts to occur. The PC is pushed onto the stack when a CALL or RCALL instruction is executed or an interrupt is Acknowledged. The PC value is pulled off the stack on a RETURN, RETLW or RETFIE instruction. PCLATU and PCLATH are not affected by any of the RETURN or CALL instructions.

The stack operates as a 31-word by 21-bit RAM and a 5-bit Stack Pointer, STKPTR. The stack space is not part of either program or data space. The Stack Pointer is readable and writable and the address on the top of the stack is readable and writable through the top-of-stack Special Function Registers. Data can also be pushed to, or popped from the stack, using these registers.

A CALL type instruction causes a push onto the stack; the Stack Pointer is first incremented and the location pointed to by the Stack Pointer is written with the contents of the PC (already pointing to the instruction following the CALL). A RETURN type instruction causes a pop from the stack; the contents of the location pointed to by the STKPTR are transferred to the PC and then the Stack Pointer is decremented.

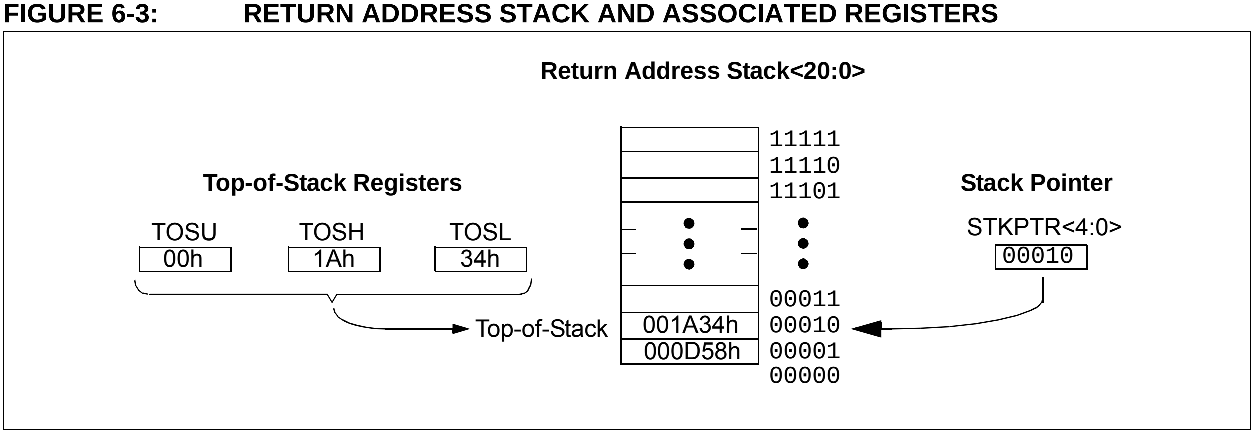
The Stack Pointer is initialized to '00000' after all Resets. There is no RAM associated with the location corresponding to a Stack Pointer value of '00000'; this is only a Reset value. Status bits indicate if the stack is full or has overflowed or has underflowed.

6.1.4.1 Top-of-Stack Access

Only the top of the return address stack (TOS) is readable and writable. A set of three registers, TOSU:TOSH:TOSL, hold the contents of the stack location pointed to by the STKPTR register (Figure 6-3). This allows users to implement a software stack if necessary. After a CALL, RCALL or interrupt, the software can read the pushed value by reading the TOSU:TOSH:TOSL registers. These values can be placed on a user-defined software stack. At return time, the software can return these values to TOSU:TOSH:TOSL and do a return.

The user must disable the global interrupt enable bits while accessing the stack to prevent inadvertent stack corruption.

FIGURE 6-3: RETURN ADDRESS STACK AND ASSOCIATED REGISTERS



6.4.3.1 FSR Registers and the INDF Operand

At the core of Indirect Addressing are three sets of registers: FSR0, FSR1 and FSR2. Each represents a pair of 8-bit registers, FSRnH and FSRnL. The four upper bits of the FSRnH register are not used, so each FSR pair holds a 12-bit value. This represents a value that can address the entire range of the data memory in a linear fashion. The FSR register pairs, then, serve as pointers to data memory locations.

Indirect Addressing is accomplished with a set of Indirect File Operands, INDF0 through INDF2. These can be thought of as “virtual” registers; they are mapped in the SFR space but are not physically implemented. Reading or writing to a particular INDF register actually accesses its corresponding FSR register pair. A read from INDF1, for example, reads the data at the address indicated by FSR1H:FSR1L. Instructions that use the INDF registers as operands actually use the contents of their corresponding FSR as a pointer to the instruction’s target. The INDF operand is just a convenient way of using the pointer.

Because Indirect Addressing uses a full 12-bit address, data RAM banking is not necessary. Thus, the current contents of the BSR and the Access RAM bit have no effect on determining the target address.

6.4.3.2 FSR Registers and POSTINC, POSTDEC, PREINC and PLUSW

In addition to the INDF operand, each FSR register pair also has four additional indirect operands. Like INDF, these are “virtual” registers that cannot be indirectly read or written to. Accessing these registers actually accesses the associated FSR register pair, but also performs a specific action on it stored value. They are:

- POSTDEC: accesses the FSR value, then automatically decrements it by 1 afterwards
- POSTINC: accesses the FSR value, then automatically increments it by 1 afterwards
- PREINC: increments the FSR value by 1, then uses it in the operation
- PLUSW: adds the signed value of the W register (range of -127 to 128) to that of the FSR and uses the new value in the operation.

In this context, accessing an INDF register uses the value in the FSR registers without changing them. Similarly, accessing a PLUSW register gives the FSR value offset by that in the W register; neither value is actually changed in the operation. Accessing the other virtual registers changes the value of the FSR registers.

Operations on the FSRs with POSTDEC, POSTINC and PREINC affect the entire register pair; that is, rollovers of the FSRnL register, from FFh to 00h, carry over to the FSRnH register. On the other hand, results of these operations do not change the value of any flags in the STATUS register (e.g., Z, N, OV, etc.).

FIGURE 6-8: INDIRECT ADDRESSING

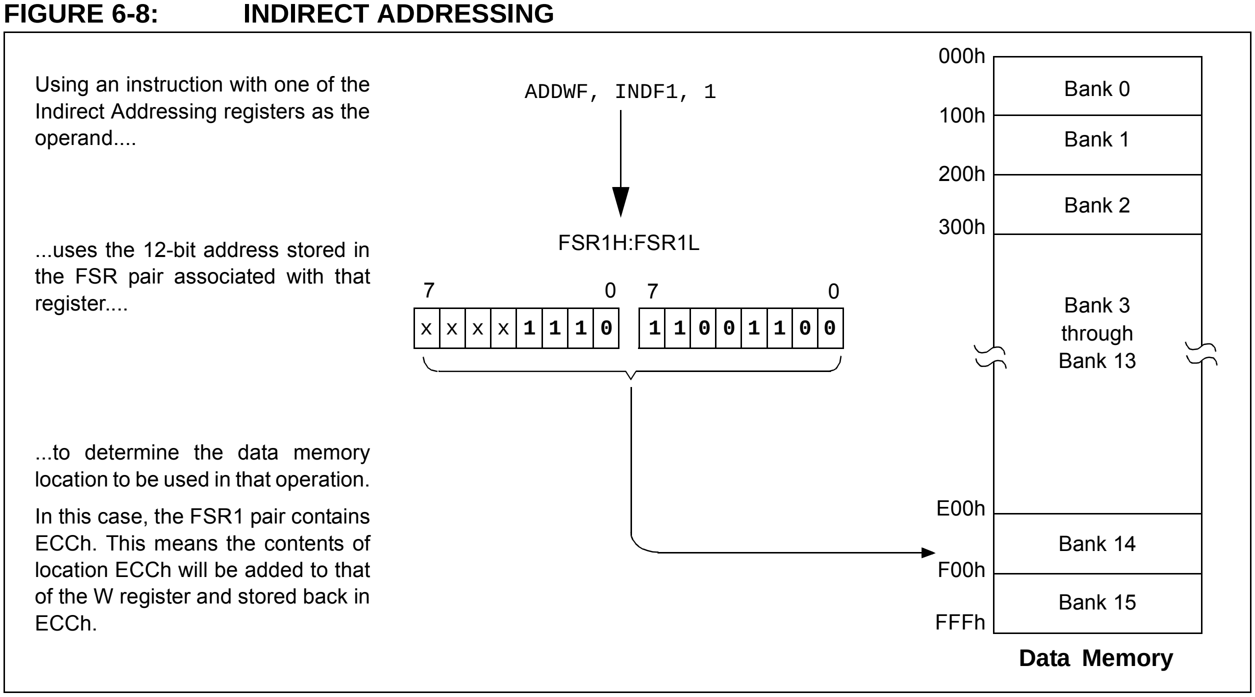
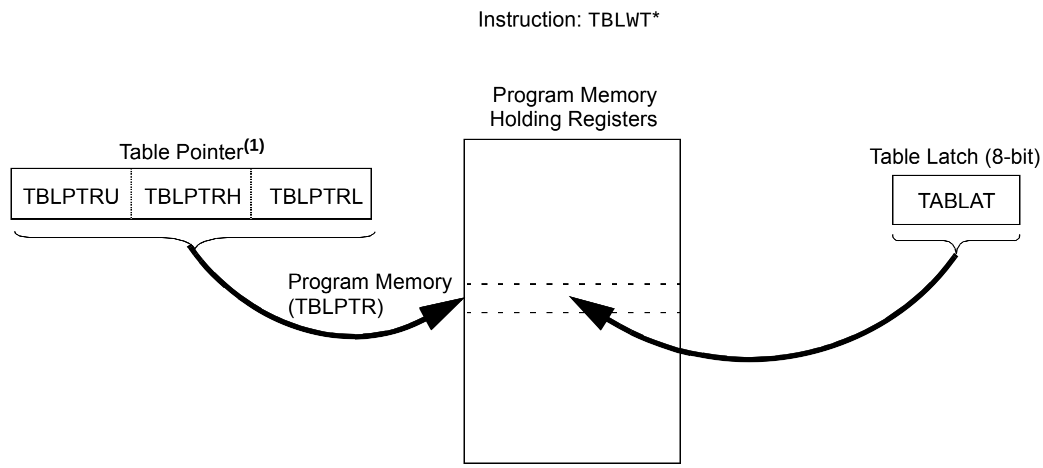


FIGURE 7-2: TABLE WRITE OPERATION



Note 1: Table Pointer actually points to one of 64 holding registers, the address of which is determined by TBLPTRL<5:0>. The process for physically writing data to the program memory array is discussed in **Section 7.5 "Writing to Flash Program Memory"**.

7.2 Control Registers

Several control registers are used in conjunction with the `TBLRD` and `TBLWT` instructions. These include the:

- EECON1 register
- EECON2 register
- TABLAT register
- TBLPTR registers

7.2.1 EECON1 AND EECON2 REGISTERS

The EECON1 register (Register 7-1) is the control register for memory accesses. The EECON2 register is not a physical register; it is used exclusively in the memory write and erase sequences. Reading EECON2 will read all '`0`'s.

The FREE bit, when set, will allow a program memory erase operation. When FREE is set, the erase operation is initiated on the next WR command. When FREE is clear, only writes are enabled.

The WREN bit, when set, will allow a write operation. On power-up, the WREN bit is clear. The WRERR bit is set in hardware when the WR bit is set and cleared when the internal programming timer expires and the write operation is complete.

Note:	During normal operation, the WRERR is read as '`1`'. This can indicate that a write operation was prematurely terminated by a Reset, or a write operation was attempted improperly.

The WR control bit initiates write operations. The bit cannot be cleared, only set, in software; it is cleared in hardware at the completion of the write operation.

14.3 Compare Mode

In Compare mode, the 16-bit CCPRx register value is constantly compared against the TMR1 register value. When a match occurs, the CCPx pin can be:

- driven high
- driven low
- toggled (high-to-low or low-to-high)
- remain unchanged (that is, reflects the state of the I/O latch)

The action on the pin is based on the value of the mode select bits (CCPxM<3:0>). At the same time, the interrupt flag bit, CCPxIF, is set.

14.3.1 CCP PIN CONFIGURATION

The user must configure the CCPx pin as an output by clearing the appropriate TRIS bit.

Note:	Clearing the CCP2CON register will force the RB3 or RC1 compare output latch (depending on device configuration) to the default low level. This is not the PORTB or PORTC I/O data latch.

14.3.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

14.3.3 SOFTWARE INTERRUPT MODE

When the Generate Software Interrupt mode is chosen (CCPxM<3:0> = `1010`), the corresponding CCPx pin is not affected. Only a CCP interrupt is generated, if enabled and the CCPxIE bit is set.

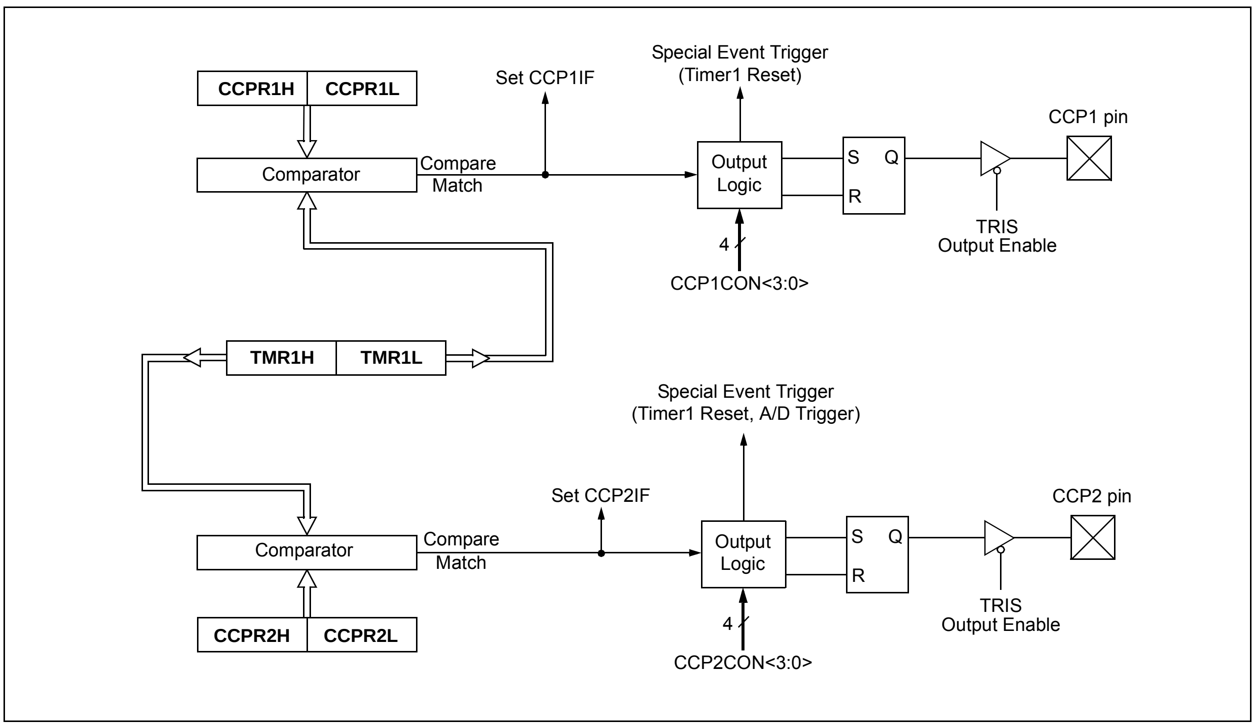
14.3.4 SPECIAL EVENT TRIGGER

Both CCP modules are equipped with a Special Event Trigger. This is an internal hardware signal generated in Compare mode to trigger actions by other modules. The Special Event Trigger is enabled by selecting the Compare Special Event Trigger mode (CCPxM<3:0> = `1011`).

For either CCP module, the Special Event Trigger resets the Timer register pair for whichever timer resource is currently assigned as the module's time base. This allows the CCPRx registers to serve as a Programmable Period register for either timer.

The Special Event Trigger for CCP2 can also start an A/D conversion. In order to do this, the A/D converter must already be enabled.

FIGURE 14-2: COMPARE MODE OPERATION BLOCK DIAGRAM



16.4.3.3 Reception

When the R/$\overline{W}$ bit of the address byte is clear and an address match occurs, the R/$\overline{W}$ bit of the SSPxSTAT register is cleared. The received address is loaded into the SSPxBUF register and the SDAx line is held low ($\overline{ACK}$).

When the address byte overflow condition exists, then the no Acknowledge ($\overline{ACK}$) pulse is given. An overflow condition is defined as either bit, BF (SSPxSTAT<0>), is set, or bit, SSPOV (SSPxCON1<6>), is set.

An MSSP interrupt is generated for each data transfer byte. The interrupt flag bit, SSPxIF, must be cleared in software. The SSPxSTAT register is used to determine the status of the byte.

If SEN is enabled (SSPxCON2<0> = 1), SCKx/SCLx (RC3 or RD0) will be held low (clock stretch) following each data transfer. The clock must be released by setting bit, CKP (SSPxCON1<4>). See **Section 16.4.4 “Clock Stretching”** for more details.

16.4.3.4 Transmission

When the R/$\overline{W}$ bit of the incoming address byte is set and an address match occurs, the R/$\overline{W}$ bit of the SSPxSTAT register is set. The received address is loaded into the SSPxBUF register. The $\overline{ACK}$ pulse will be sent on the ninth bit and pin RC3 or RD6 is held low, regardless of SEN (see **Section 16.4.4 “Clock Stretching”** for more details). By stretching the clock, the master will be unable to assert another clock pulse until the slave is done preparing the transmit data. The transmit data must be loaded into the SSPxBUF register which also loads the SSPxSR register. Then pin RC3 or RD0 should be enabled by setting bit, CKP (SSPxCON1<4>). The eight data bits are shifted out on the falling edge of the SCLx input. This ensures that the SDAx signal is valid during the SCLx high time (Figure 16-9).

The $\overline{ACK}$ pulse from the master-receiver is latched on the rising edge of the ninth SCLx input pulse. If the SDAx line is high (not $\overline{ACK}$), then the data transfer is complete. In this case, when the $\overline{ACK}$ is latched by the slave, the slave logic is reset (resets SSPxSTAT register) and the slave monitors for another occurrence of the Start bit. If the SDAx line was low ($\overline{ACK}$), the next transmit data must be loaded into the SSPxBUF register. Again, pin RC3 or RD0 must be enabled by setting bit CKP.

An MSSP interrupt is generated for each data transfer byte. The SSPxIF bit must be cleared in software and the SSPxSTAT register is used to determine the status of the byte. The SSPxIF bit is set on the falling edge of the ninth clock pulse.

16.4.7.2 Clock Arbitration

Clock arbitration occurs when the master, during any receive, transmit or Repeated Start/Stop condition, deasserts the SCLx pin (SCLx allowed to float high). When the SCLx pin is allowed to float high, the Baud Rate Generator (BRG) is suspended from counting until the SCLx pin is actually sampled high. When the SCLx pin is sampled high, the Baud Rate Generator is reloaded with the contents of SSPxADD<6:0> and begins counting. This ensures that the SCLx high time will always be at least one BRG rollover count in the event that the clock is held low by an external device (Figure 16-18).

FIGURE 16-18: BAUD RATE GENERATOR TIMING WITH CLOCK ARBITRATION

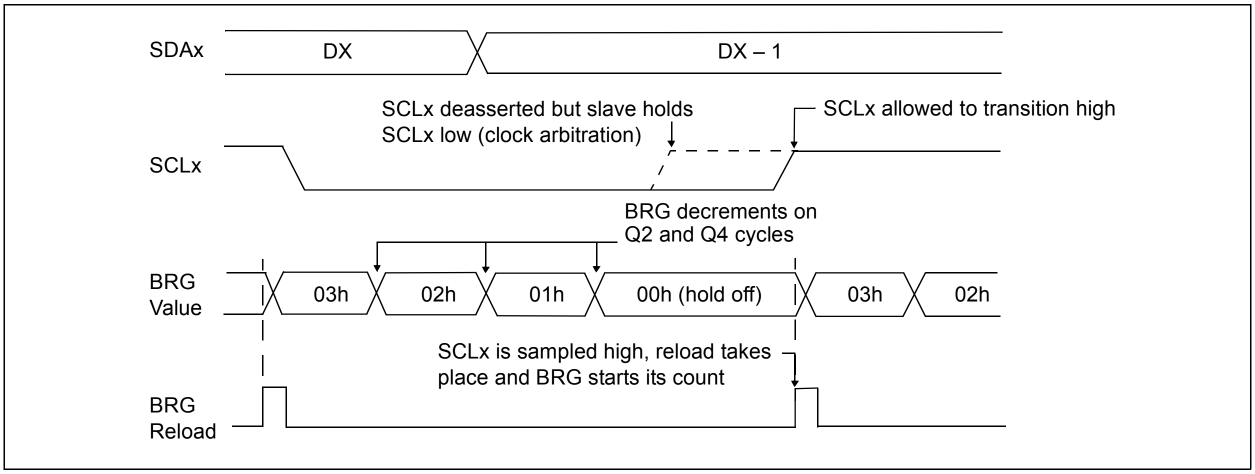
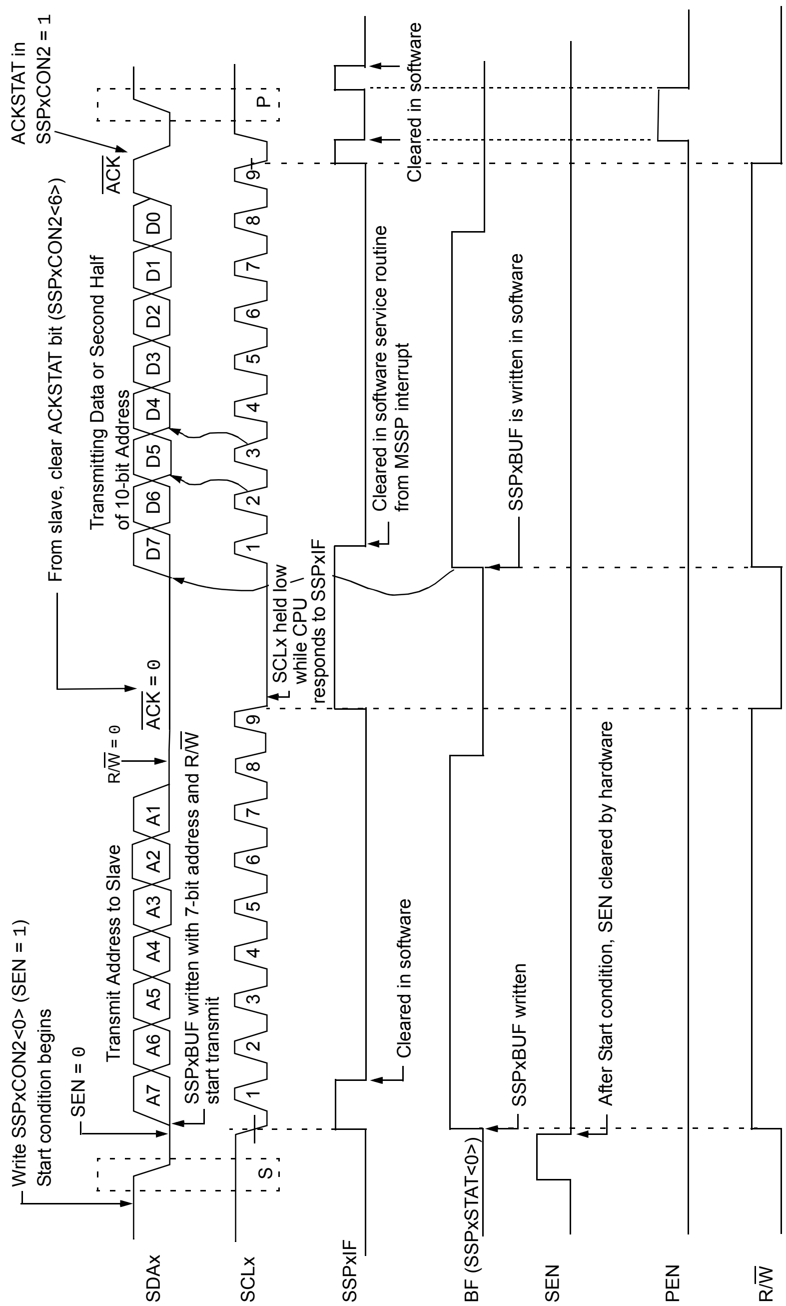


FIGURE 16-21: I^2C™ MASTER MODE WAVEFORM (TRANSMISSION, 7 OR 10-BIT ADDRESSING)



16.4.17.2 Bus Collision During a Repeated Start Condition

During a Repeated Start condition, a bus collision occurs if:

a) A low level is sampled on SDAx when SCLx goes from low level to high level.
b) SCLx goes low before SDAx is asserted low, indicating that another master is attempting to transmit a data '1'.

When the user deasserts SDAx and the pin is allowed to float high, the BRG is loaded with SSPxADD<6:0> and counts down to 0. The SCLx pin is then deasserted and when sampled high, the SDAx pin is sampled.

If SDAx is low, a bus collision has occurred (i.e., another master is attempting to transmit a data '0', see Figure 16-29). If SDAx is sampled high, the BRG is reloaded and begins counting. If SDAx goes from high-to-low before the BRG times out, no bus collision occurs because no two masters can assert SDAx at exactly the same time.

If SCLx goes from high-to-low before the BRG times out and SDAx has not already been asserted, a bus collision occurs. In this case, another master is attempting to transmit a data '1' during the Repeated Start condition (see Figure 16-30).

If, at the end of the BRG time-out, both SCLx and SDAx are still high, the SDAx pin is driven low and the BRG is reloaded and begins counting. At the end of the count, regardless of the status of the SCLx pin, the SCLx pin is driven low and the Repeated Start condition is complete.

FIGURE 16-29: BUS COLLISION DURING A REPEATED START CONDITION (CASE 1)

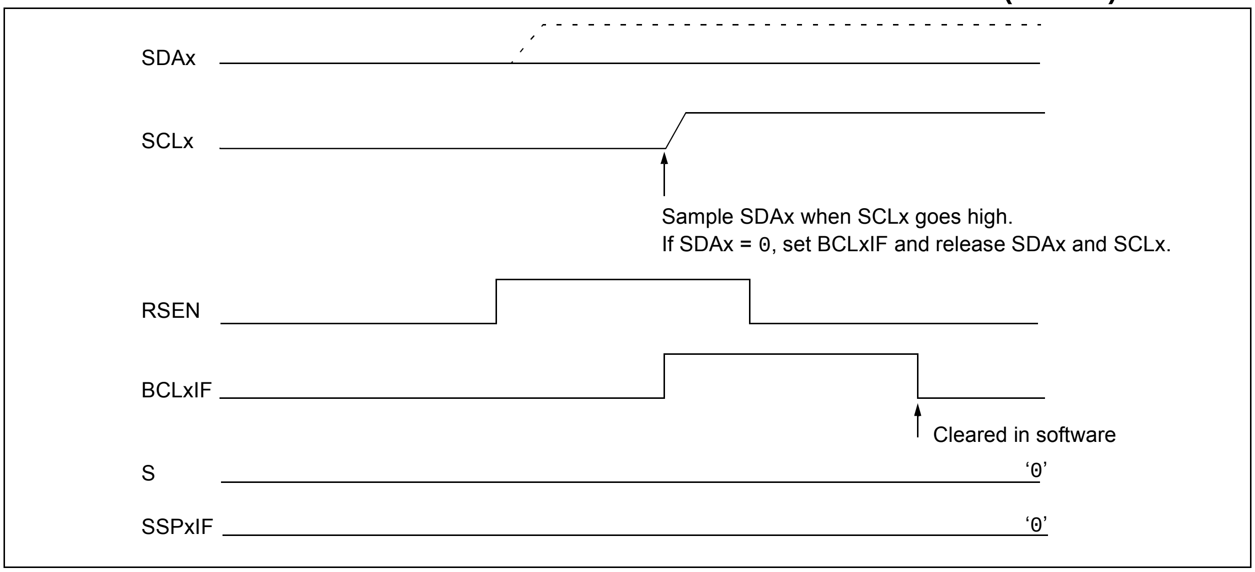
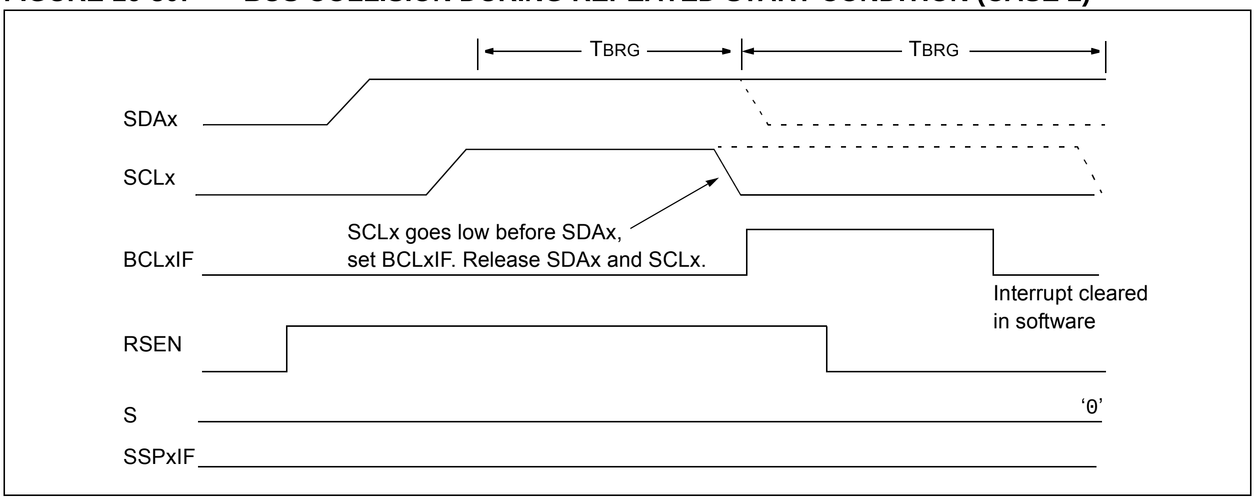


FIGURE 16-30: BUS COLLISION DURING REPEATED START CONDITION (CASE 2)



16.4.17.3 Bus Collision During a Stop Condition

Bus collision occurs during a Stop condition if:

a) After the SDAx pin has been deasserted and allowed to float high, SDAx is sampled low after the BRG has timed out.

b) After the SCLx pin is deasserted, SCLx is sampled low before SDAx goes high.

The Stop condition begins with SDAx asserted low. When SDAx is sampled low, the SCLx pin is allowed to float. When the pin is sampled high (clock arbitration), the Baud Rate Generator is loaded with SSPxADD<6:0> and counts down to 0. After the BRG times out, SDAx is sampled. If SDAx is sampled low, a bus collision has occurred. This is due to another master attempting to drive a data '0' (Figure 16-31). If the SCLx pin is sampled low before SDAx is allowed to float high, a bus collision occurs. This is another case of another master attempting to drive a data '0' (Figure 16-32).

FIGURE 16-31: BUS COLLISION DURING A STOP CONDITION (CASE 1)

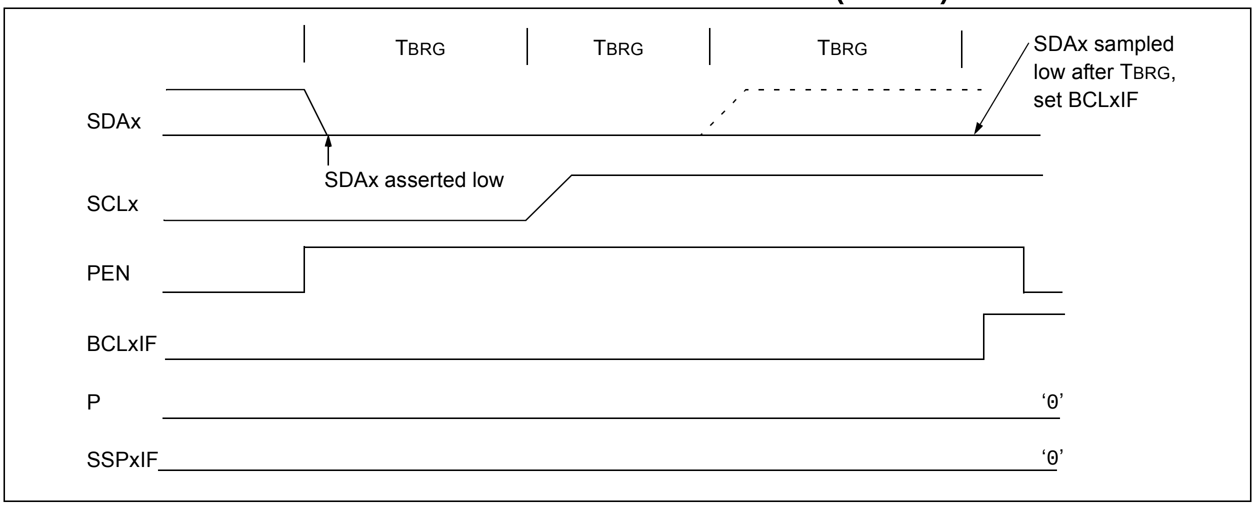
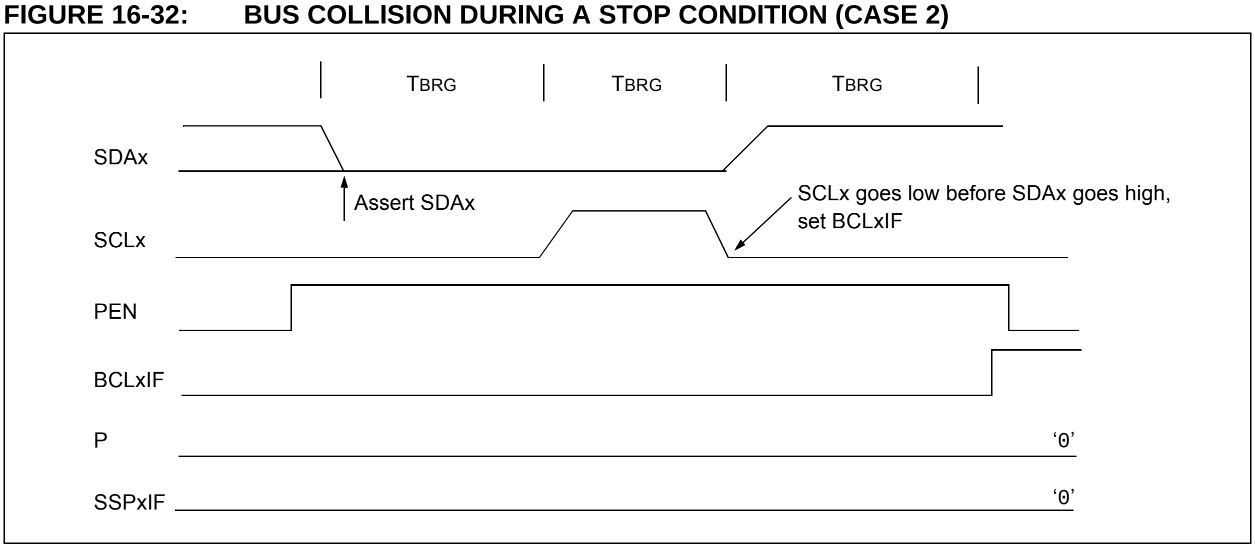


FIGURE 16-32: BUS COLLISION DURING A STOP CONDITION (CASE 2)



17.4 EUSART Synchronous Slave Mode

Synchronous Slave mode is entered by clearing bit, CSRC (TXSTA<7>). This mode differs from the Synchronous Master mode in that the shift clock is supplied externally at the CK pin (instead of being supplied internally in Master mode). This allows the device to transfer or receive data while in any low-power mode.

17.4.1 EUSART SYNCHRONOUS SLAVE TRANSMISSION

The operation of the Synchronous Master and Slave modes is identical, except in the case of the Sleep mode.

If two words are written to the TXREG and then the SLEEP instruction is executed, the following will occur:

a) The first word will immediately transfer to the TSR register and transmit.

b) The second word will remain in the TXREG register.

c) Flag bit, TXIF, will not be set.

d) When the first word has been shifted out of TSR, the TXREG register will transfer the second word to the TSR and flag bit, TXIF, will now be set.

e) If enable bit, TXIE, is set, the interrupt will wake the chip from Sleep. If the global interrupt is enabled, the program will branch to the interrupt vector.

To set up a Synchronous Slave Transmission:

1. Enable the synchronous slave serial port by setting bits, SYNC and SPEN, and clearing bit, CSRC.
2. Clear bits, CREN and SREN.
3. If interrupts are desired, set enable bit, TXIE.
4. If 9-bit transmission is desired, set bit, TX9.
5. Enable the transmission by setting enable bit, TXEN.
6. If 9-bit transmission is selected, the ninth bit should be loaded in bit, TX9D.
7. Start transmission by loading data to the TXREG register.
8. If using interrupts, ensure that the GIE and PEIE bits in the INTCON register (INTCON<7:6>) are set.

TABLE 17-9: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	47
PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	49
PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	49
IPR1	PSPIP(1)	ADIP	RCIP	TXIP	SSP1IP	CCP1IP	TMR2IP	TMR1IP	49
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	49
TXREG	EUSART Transmit Register								49
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	49
BAUDCON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	49
SPBRGH	EUSART Baud Rate Generator Register High Byte								49
SPBRG	EUSART Baud Rate Generator Register Low Byte								49

Legend: — = unimplemented, read as '0'. Shaded cells are not used for synchronous slave transmission.

Note 1: These bits are not implemented on 28-pin devices and should be read as '0'.

NOTES:

The analog reference voltage is software selectable to either the device's positive and negative supply voltage (V_{DD} and V_{SS}), or the voltage level on the RA3/AN3/V_{REF}+ and RA2/AN2/V_{REF}-/CV_{REF} pins.

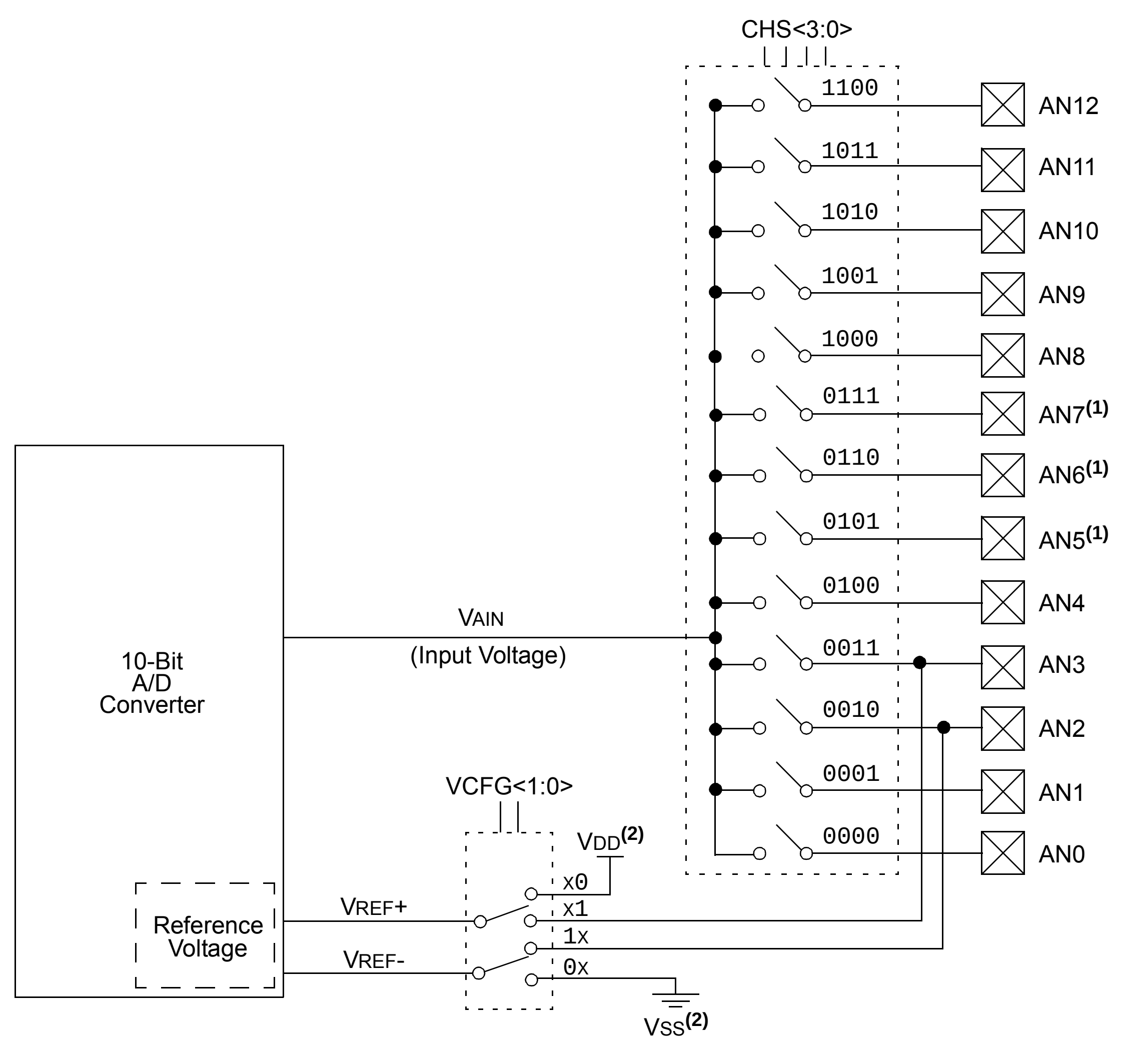
The A/D converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

The output of the sample and hold is the input into the converter, which generates the result via successive approximation.

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off and any conversion in progress is aborted.

Each port pin associated with the A/D converter can be configured as an analog input, or as a digital I/O. The ADRESH and ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRESH:ADRESL register pair, the GO/DONE bit (ADCON0 register) is cleared and A/D Interrupt Flag bit, ADIF, is set. The block diagram of the A/D module is shown in Figure 18-1.

FIGURE 18-1: A/D BLOCK DIAGRAM



Note 1: Channels AN5 through AN7 are not available in 28-pin devices.

2: I/O pins have diode protection to V_{DD} and V_{SS}.

24.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings(†)

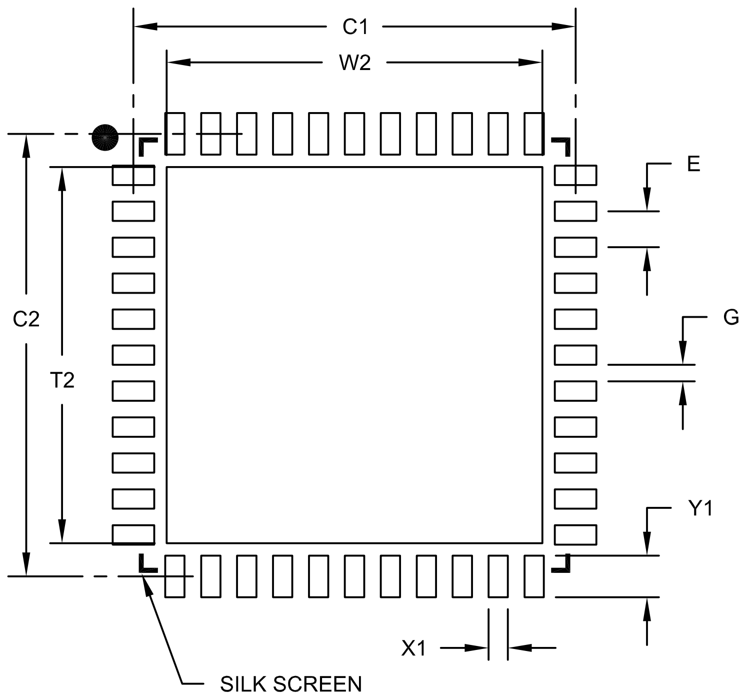
Ambient temperature under bias .... -40°C to +100°C
Storage temperature .... -65°C to +150°C
Voltage on any digital-only input $\overline{MCLR}$ I/O pin with respect to V_{SS} .... -0.3V to 6.0V
Voltage on any combined digital and analog pin with respect to V_{SS} .... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DDCORE} with respect to V_{SS} .... -0.3V to 2.75V
Voltage on V_{DD} with respect to V_{SS} .... -0.3V to 4.0V
Total power dissipation **(Note 1)** 1.0W
Maximum current out of V_{SS} pin .... 300 mA
Maximum current into V_{DD} pin .... 250 mA
Maximum output current sunk by any PORTB and PORTC I/O pin .... 25 mA
Maximum output current sunk by any PORTA, PORTD, and PORTE I/O pin .... 4 mA
Maximum output current sourced by any PORTB and PORTC I/O pin .... 25 mA
Maximum output current sourced by any PORTA, PORTD, and PORTE I/O pin .... 4 mA
Maximum current sunk by all ports combined .... 200 mA
Maximum current sourced by all ports combined .... 200 mA

Note 1: Power dissipation is calculated as follows:
$Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

† **NOTICE:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			6.80
Optional Center Pad Length	T2			6.80
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.80
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103A

NOTES: